

ABSTRACT

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING
THE SAME

Embodiments relate to a semiconductor device and a method of manufacturing the same.

5 In one embodiment, a semiconductor device includes a first substrate including first and second regions on its surface, a first control circuit on the first substrate in the first region, a first memory cell array above the first control circuit in the first region and connected to the first control circuit, and a first pad
10 above the first memory cell array in the first region and connected to the first control circuit. The device further includes a second control circuit on the first substrate in the second region, a second memory cell array above the second control circuit in the second region and connected to the second
15 control circuit, a second pad above the second memory cell array in the second region and connected to the second control circuit, and a connection line above the first and second memory cell arrays and connecting the first and second pads.

20 The embodiment can efficiently manufacture semiconductor chips.

(FIG. 4)